



## **SPECIFICATION** (Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL05B102JB5NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1nF, 50V, ±5%, X7R, 0402

## A. Samsung Part Number

<u>CL</u> <u>05</u> <u>B</u> <u>102</u> <u>J</u> <u>B</u> <u>5</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Se	ries Sam	Samsung Multi-layer Ceramic Capacitor						
② Siz	<b>ze</b> 040	2 (inch code) L:	1.0	± 0.05	mm	W:	$0.5 \pm 0.05$	mm
3 Die	electric X	7R	8	Inner ele	ctrode	N	li	
4 Ca	pacitance	<b>1</b> nF		Terminat	ion	С	u	
⑤ Ca	pacitance :	±5 %		Plating		S	n 100%	(Pb Free)
tol	erance		9	Product		Ν	lormal	
⑥ Ra	ited Voltage	50 V	10	Special		R	eserved for	future use
⑦ Th	ickness 0	.5 ± 0.05 mm	11)	Packagir	ng	С	ardboard T	ype, 7" reel

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition				
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms				
Tan δ (DF)	0.025 max.					
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance	Whichever is Smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	250% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	X7R					
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)				
		with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5°C, 3±0.3sec.				
		(preheating : 80~120 ℃ for 10~30sec.)				
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	Tan δ, IR : initial spec.					

	Performance	Test condition				
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ: 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs				
	IR: 25MΩ·μF or Over					
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.05 max	Max. operating temperature				
	IR: $50 \text{M}\Omega \cdot \mu \text{F}$ or Over					
		1000+48/-0hrs				
Temperature	Capacitance change: within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature $\rightarrow$ 25 $^{\circ}$ C				
		→ Max. operating temperature → 25°C				
		5 cycle test				

## C. Recommended Soldering method:

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.